

D2FP

Ultra Subminiature Basic Switch

Optical Ultra Subminiature Basic Switches for operations with rapid response and high reliability

- Rapid, chattering-free response due to contactless operation using photosensors
- High reliability achieved by improved resistance against environment change
- · Long durability achieved using a stable spring structure
- Easy mounting achieved by integrating the sensors inside the switch
- · Clear click feeling



Refer to "Precautions" on page 4.

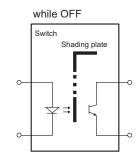
Model Number Legend

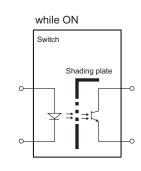
D2FP- [1) (2)

(1) Operating Force (OF) F: 0.59±0.15 N (2) Output Type
N2: 1 output type

Contact Form

SPST-NO





List of Models

Operating Force (OF)	Durability	Button color	Model	Minimum packing unit
0.59 N	70,000,000 operations min.	WHITE	D2FP-FN2	500 pcs.



D2FP

Characteristics/Ratings/Electrical Characteristics

Characteristics

		D2FP-FN2		
Operating speed		1 to 500 mm/s		
Operating frequency	Mechanical/ Electrical	300 operations/1 min. max.		
Vibration resistance	Malfunction	10 to 55 Hz, 1.5 mm double amplitude		
Shock	Destruction	1,000 m/s² max.		
resistance	Malfunction	300 m/s² max.		
Durability		70,000,000 operations min. (at 300 ops./1 min.)		
Ambient operating temperature		+5 to +40°C (at 60% RH max.) (with no icing or condensation)		
Weight		Approx. 0.54 g		

Absolute Maximum Ratings (Ta = 25°C)

Item		Symbol	Max. rating	Unit
	Forward current	lF	40	mA
Input	Peak surge forward current (tp = 100 µs)	lгsм	200	mA
	Reverse voltage	VR	5	V
	Collector dissipation	Pc	75	mW
Output	Collector current	Ic	20	mA
Catput	Collector-emitter voltage	Vceo	30	V

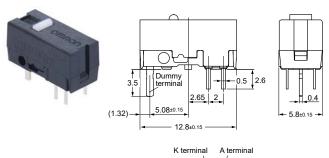
Electrical Characteristics (Ta = 25°C)

Item		Symbol	Min.	Тур.	Max.	Unit	Condition	
Input	Forward voltage	VF		1.16	1.4	V	I _F =5 mA	
	Reverse current	lR			10	μΑ	V _R =5 V	
Output	Dark current	Iceo			100	nA	Vce=10 V	
	Collector-emitter saturated voltage	VCE(SAT)			0.4	V	Ic=100 μA E _e =1 mW/cm ²	
Transmission characteristics	Collector current while ON	IC(on)	0.75	1.07	1.35	mA	Vce=5 V, Ee=1 mW/cm ²	
	Rising time	Tr		100		μs	V _{CE} =2 V I _C =1 mA	
	Falling time	Tf			21	μs	I _F =5 mA (Pulse drive: 30 μs ON,	
	Collector-emitter voltage while ON	Vce ON			0.4	V	970 µs OFF) Ambient temperature: 20 ± 15°C Ambient humidity: 65 ± 20%RH	
	Collector-emitter voltage while OFF	Vce OFF	1.5			V	Operating frequency: 300 operations/1 min.	

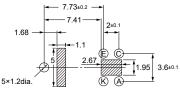
Dimensions (Unit: mm) / Operating Characteristics

CAD Date marked products, 2D drawings and 3D CAD models are available. For CAD information, please visit our website, which is noted on the last page.

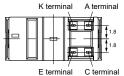
D2FP-FN2 CAD Data

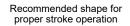


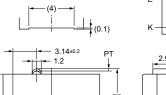
<PCB pad dimensions (reference)>



Do not connect the dummy terminal to the circuit. Wiring is prohibited in the shaded areas.

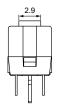






Internal circuit





Terminal No.	Name	
Α	Anode	
K	Cathode	
С	Collector	
E	Emitter	

		D2FP-FN2
Operating Force	OF	0.59±0.15 N
Releasing Force	RF	0.24 N min.
Pretravel	PT	0.3±0.2 mm
Free Position	FP	7.35 +0/-0.4

 $\textbf{Note:} \ \ \textbf{Unless otherwise specified, a tolerance of } \pm 0.4 \ \text{mm applies to all dimensions.}$

D₂FP

Precautions

★Refer to General Information.

Cautions

Electrical Ratings

 Use the Switch within the rated voltage and current ranges, otherwise the Switch may have a shortened durability, radiate heat, or burn out. This particularly applies to the instantaneous voltages and currents when switching.

Correct Use

Soldering

- Before soldering the Switch on a multilayer PCB, test to confirm that soldering can be performed properly. Switch may experience deformation due to heat, depending on the PCB type, the pattern and lands that are used, etc.
- When using an automatic solder bath, it is recommended to preheat to 100°C within 60 seconds, and heat to 230 to 260°C within 5 seconds (single-sided board) or within 3 seconds (double-sided board). In addition, ensure that the liquid surface level of the solder and flux do not exceed the board.
- For manual soldering, ensure that the heating time is within 3 seconds using a soldering iron with a tip temperature of 350°C or less, and be sure not to apply external force for around one minute after soldering. In addition, supply the solder away from the switch case and ensure that the solder and flux do not flow to the case side. If flux enters inside the switches they may malfunction.
- Solder within 72 hours after opening the moisture-proof packaging.
 For products for which over 72 hours have elapsed, perform baking for 24 hours at 80°C before soldering.

Washing

The Switch is not sealed, and cannot be washed.
 Doing so will cause the washing agent, together with flux or dust particles on the PCB, to enter the Switch, resulting in malfunction.

Application Environment

 Do not use the Switch in locations that are subject to toxic gas, silicon, excessive dust, excessive dirt, high temperatures, high humidity, sudden temperature changes, water splashes, or oil splashes.

Otherwise, functional damage resulting from damage due to defective characteristics or corrosion may occur.

Other Precautions

- · When using this product, antistatic measures are required.
- Storing it in a container sealed with nitrogen flush packaging or with a desiccant is recommended.

MEMO

Please check each region's Terms & Conditions by region website.

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Device & Module Solutions Company

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